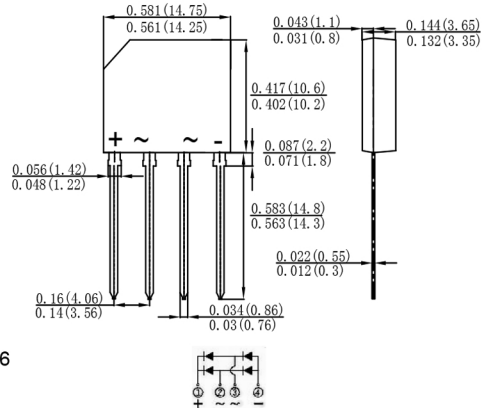


### Features

- ◆ Glass Passivated Chip Junction
- ◆ Glass passivated die construction
- ◆ Low forward voltage drop
- ◆ High current capability
- ◆ High surge current capability
- ◆ The Plastic material-has UL flammability 94V-0

### GBP



Dimensions in inches and (millimeters)

### Mechanical Data

**Case :** JEDEC KBP Molded plastic body

**Terminals :** Solder plated, solderable per MIL-STD-750,Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

**Weight :** 0.050 ounce, 1.52 grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RCD KBP4005	RCD KBP401	RCD KBP402	RCD KBP404	RCD KBP406	RCD KBP408	RCD KBP410	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward output rectified current at $T_c=100^\circ\text{C}$ (With heatsink) (Without heatsink)	$I_{(AV)}$	4.0				2.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$					75.0			A
Maximum instantaneous forward voltage drop per bridge element at 4.0A	$V_F$					1.1			V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$					5.0			$\mu\text{A}$
						0.5			mA
$I^2t$ Rating for fusing (3ms $\leq t \leq$ 8.3ms)	$I^2t$					23.3			A <sup>2</sup> S
Typical Junction Capacitance per element (Note 2)	$C_j$					50			pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$					40			$^\circ\text{C}/\text{W}$
	$R_{\theta JC}$					14			
	$R_{\theta JL}$					20			
Operating junction temperature range	$T_J$					-55 to +150			$^\circ\text{C}$
Storage temperature range	$T_{STG}$					-55 to +150			$^\circ\text{C}$

Note:1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

Fig.1 Forward Current Derating Curve

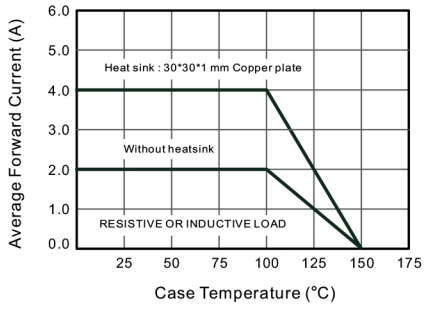


Fig.2 Typical Instantaneous Reverse Characteristics

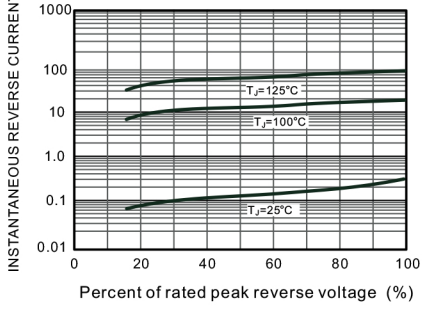


Fig.3 Typical Forward Characteristic

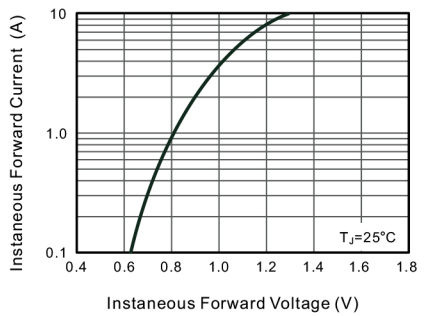


Fig.4 Typical Junction Capacitance

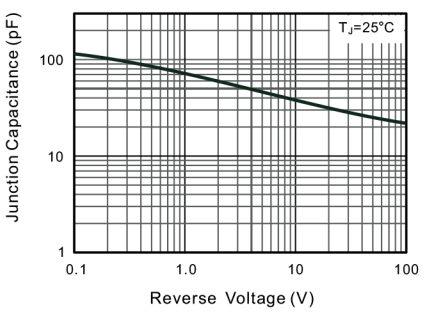


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

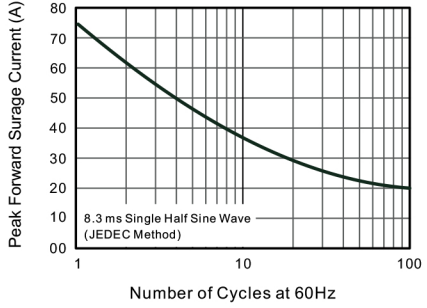
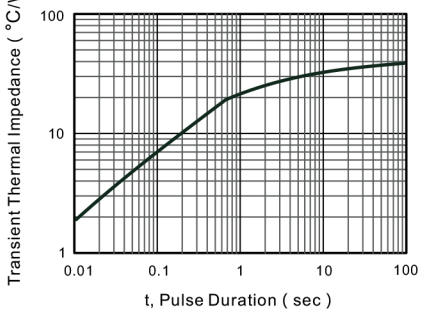


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.